Abstract

Method for the Production of Transistor Structures with LDD

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The substrate (1) is etched such that on the source side and on the drain side downward sloping sidewalls (5) are formed adjacent to the gate electrode (3) and sloping downward from it. Spacers (7) are positioned there. An implantation (9) of dopant is performed at a low angle relative to the upper surface, through the spacers (7), in order to form the regions (11) of lower dopant concentration, and an implantation (10) of dopant is performed at a high angle relative to the upper surface in order to form the source and drain regions (12).

Figure 6